What is Claimed is:

1. A carrier module comprising:

a carrier module body for seating a semiconductor device on an underside thereof, having a pass through hole from an upper part to the underside the semiconductor device is seated thereon;

a housing over the carrier module body;

a supplementary housing fitted in a lower part of the housing to be movable in up/down directions, for elastic contact with the carrier module body by a first elastic member fitted inside of the housing;

a vacuum tube in the supplementary housing so as to be in communication with the pass through hole in the carrier module body;

at least one pair of latches in a lower part of the carrier module body to move apart or close in an outer or inner side, for holding or releasing the semiconductor device seated on the carrier module body;

a latch button fitted in an upper part of the carrier module body so as to be movable in up/down directions, and coupled to the latch with a connection pin for moving in up/down directions by an external force, to making the latch to move; and

a second elastic member for elastic supporting of the latch buttons on the carrier module body,

thereby, when the semiconductor device is brought into contact with the test socket, and tested, holding the semiconductor device with a vacuum formed through the pass through hole in the carrier module body and the vacuum tube in a state the latch releases the semiconductor device.

2. The carrier module as claimed in claim 1, further comprising a heat sink in a central part of the carrier module body, for bringing into contact with a surface of the semiconductor device, and transferring heat.

3. The carrier module as claimed in claim 1, further comprising an O-ring fitted at a connection part of the supplementary housing and the carrier module body.

4. The carrier module as claimed in claim 1, wherein the latch has a slanted slot of a long hole form for inserting a guide pin therein, wherein the latch is opened or closed, as the slanted slot slides along the guide pin.

5. The carrier module as claimed in claim 1, further comprising:

a latch pusher projected upward from one side part of the test socket to be brought into contact with the semiconductor device; and

a projection projected outwardly from an outer part of the latch, for being brought into contact with the latch pusher.